

### Features

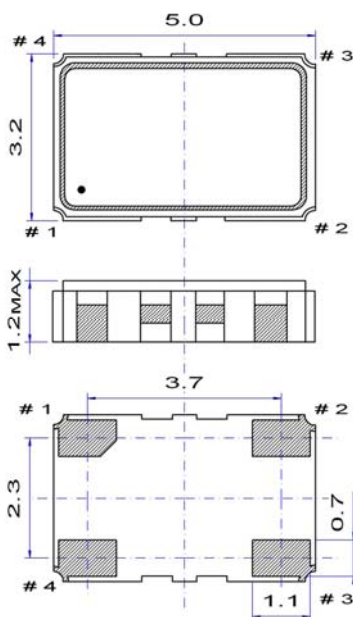
Applications: transmission, TDM networks, SDH, SONET, wireless communications, IEEE 1588v2, SyncE, STRATUM III, wireless backhaul, metro carrier Ethernet, femtocells, picocells  
 Holdover stability:  $\pm 0.37$  ppm over 24 h  
 Overall stability:  $\pm 4.60$  ppm including 20 years aging  
 Output signal: CMOS

### Specification

Parameter	Specification	
Frequency range	10.0 ~ 26.0 MHz	
Standard frequencies	19.440, 20.0, 25.0 & 26.0 MHz	
Frequency stability:	$\leq \pm 4.60$ ppm	overall stability including 20 years aging
vs. temperature	$\leq \pm 0.28$ ppm	-40 ~ +85 °C
vs. aging	$\leq \pm 3.0$ ppm	20 years
Holdover stability <sup>(1)</sup>	$\leq \pm 0.37$ ppm	over 24 hours
Frequency tolerance ex. factory	$\leq \pm 0.50$ ppm	@ +25 °C
Supply voltage	+3.3 V or +5.0 V	$\pm 5$ %
Supply current	< 6 mA	
Output signal	CMOS	
Output load	15 pF	$\pm 5$ %
Tri-state function	pin #1 high or open pin #1 low	pin #3 → oscillation pin #3 → high impedance
Phase noise @ 20.0 MHz carrier frequency	-145 dBc/Hz	@ 10 kHz
Operating temperature range	0 ~ +70 °C -40 ~ +85 °C	indoor use outdoor use
Storage temperature range	-55 ~ +125 °C	
Packaging units	tape & reel tape only	500 or 1'000 pieces < 500 pieces
Customer specifications on request		

<sup>(1)</sup> Including: frequency stability, vs temperature, supply change of  $\pm 5$  % and aging over 24 hours

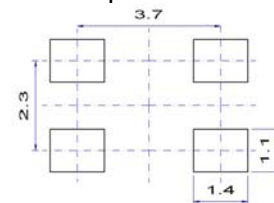
### Outline Dimensions & PIN Function & Solder Pattern



#### Pin function

- # 1 Tri-state or not connected
- # 2 GND
- # 3 Output
- # 4 Vdc

#### Example for solder pattern



**Do not design any conductive path between the pattern**

#### Example for IR reflow soldering temperature

